

PART INFORMATION	
Mfg Item Number	MPXH6300AC6T1
Mfg Item Name	SNSR SSOP 08 PORTED
SUPPLIER	
Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2013-01-08
Response Document ID	0887K50010S205A1.30
Contact Name	Freescale Semiconductor Inc
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Representative Title	EPP Customer Response
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DECLARATION	
EU RoHS	Yes
Pb Free	No
HalogenFree	No
Plating Indicator	e4
EU RoHS Exemption(s)	7c-l
MANUFACTURING	
Mfg Item Number	MPXH6300AC6T1
Mfg Item Name	SNSR SSOP 08 PORTED
Version	ALL
Weight	0.508200
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	
Peak Processing Temperature	
Max Time at Peak Temperature	
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	<p>Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.</p>
RoHS Declaration	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemptions in this part	7c-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

SubPart	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	REACHPPM	REACH%
Cap/Cover	0.0809		Metals	Chromium, metal	7440-47-3	0.014579	g	180216	18.0216	28687	2.8687
Cap/Cover		Solvents, additives, and other materials	Sulfur	7704-34-9	0.000024	g	300	0.03		47	0.0047
Cap/Cover		Solvents, additives, and other materials	Phosphorus	7723-14-0	0.000032	g	400	0.04		62	0.0062
Cap/Cover		Solvents, additives, and other materials	Silicon	7440-21-3	0.000607	g	7509	0.7509		1194	0.1194
Cap/Cover		Metals	Iron, metal	7439-89-6	0.064848	g	801563	80.1563		127605	12.7605
Cap/Cover		Metals	Manganese, metal	7439-96-5	0.00081	g	10012	1.0012		1593	0.1593
Non-Conductive Epoxy/Adhesive	0.0006						g				
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Silicone gum	67762-94-1	0.000006	g	10324	1.0324		11	0.0011
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Siloxanes and Silicones, di-Me, Me vinyl, vinyl group-terminated	68083-18-1	0.000074	g	122911	12.2911		145	0.0145
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Siloxanes and silicones, di-Me, vinyl group-terminated	68083-19-2	0.000236	g	393313	39.3313		464	0.0464
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Proprietary Material-Other silicones and silicones	-	0.000133	g	221238	22.1238		261	0.0261
Non-Conductive Epoxy/Adhesive		Glass	D4 and HMDS-treated Silicon Dioxide	68937-51-9	0.000088	g	147493	14.7493		173	0.0173
Non-Conductive Epoxy/Adhesive		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7	0.000056	g	93412	9.3412		110	0.011
Non-Conductive Epoxy/Adhesive		Metals	Titanium (IV) Oxide	13463-67-7	0.000007	g	11508	1.1508		13	0.0013
Port	0.1305						g				
Port		Plastics/polymers	Polyphenylene Sulfide (PPS)	26125-40-6	0.077773	g	595960	59.596		153038	15.3038
Port		Glass	Proprietary Material-Other glass compounds (without lead, chromium, cadmium or mercury)	-	0.052727	g	404040	40.404		103753	10.3753
Bonding Wire	0.0006						g				
Bonding Wire		Metals	Gold, metal	7440-57-5	0.0006	g	1000000	100		1180	0.118
Gel Die Encapsulant	0.0133						g				
Gel Die Encapsulant		Solvents, additives, and other materials	Proprietary Material-Other inorganic fluorine compounds and their aqueous salts	-	0.0133	g	1000000	100		26170	2.617
Copper Lead Frame	0.2529						g				
Copper Lead Frame		Metals	Copper, metal	7440-50-8	0.213648	g	844788	84.4788		420414	42.0414
Copper Lead Frame		Metals	Gold, metal	7440-57-5	0.000169	g	668	0.0668		332	0.0332
Copper Lead Frame		Solvents, additives, and other materials	Phosphorus	7723-14-0	0.000236	g	1289	0.1289		641	0.0641
Copper Lead Frame		Metals	Iron, metal	7439-89-6	0.004875	g	19277	1.9277		8592	0.8592
Copper Lead Frame		Metals	Nickel, metal	7440-02-0	0.002371	g	9375	0.9375		4665	0.4665
Copper Lead Frame		Metals	Palladium, metal	7440-05-3	0.000116	g	459	0.0459		228	0.0228
Copper Lead Frame		Plastics/polymers	Polyphenylene Sulfide (PPS)	26125-40-6	0.009777	g	38661	3.8661		19238	1.9238
Copper Lead Frame		Glass	Fibrous-glass-wool	65997-17-3	0.021184	g	83765	8.3765		41684	4.1684
Copper Lead Frame		Metals	Zinc, metal	7440-66-6	0.000434	g	1718	0.1718		853	0.0853
Bonding Agent	0.0163						g				
Bonding Agent		Metals	Proprietary Material-Other aluminum compounds	-	0.007335	g	450000	45		14433	1.4433
Bonding Agent		Solvents, additives, and other materials	Other guanidine compounds	-	0.000408	g	25000	2.5		802	0.0802
Bonding Agent		Solvents, additives, and other materials	Carbon Black	1333-86-4	0.000408	g	25000	2.5		802	0.0802
Bonding Agent		Plastics/polymers	Other phenolic resins	-	0.008149	g	500000	50		16035	1.6035
Pb Glass Frit Semiconductor Di	0.0131						7g-I				
Pb Glass Frit Semiconductor Di		Metals	Lead titanium oxide (PbTiO3)	12060-00-3	0.000136	g	10381	1.0381		267	0.0267
Pb Glass Frit Semiconductor Di		Glass	Fibrous-glass-wool	65997-17-3	0.000113	g	9943	0.9943		255	0.0255
Pb Glass Frit Semiconductor Di		Solvents, additives, and other materials	2,2,4-trimethyl-1,3-pentanediol-1-monoisobutyrate	25265-77-4	0.00013	g	9943	0.9943		255	0.0255
Pb Glass Frit Semiconductor Di		Glass	Silicon, doped	-	0.012704	g	969733	96.9733		24998	2.4998

LINKS

MCD LINK

Freescale website <http://www.freescale.com>**GENERAL ENVIRONMENTAL COMPLIANCE LINKS**RoHS signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ROHS_Freescale_Response.pdfChina RoHS <http://www.freescale.com/chinarohs>REACH signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_REACH_Freescale_Response.pdfELV signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ELV_Freescale_Reponse.pdfConflict Minerals statement http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_CONFLICT_METAL_Freescale_Response.pdf**FREESCALE ENVIRONMENTAL INFORMATION**EPP website <http://www.freescale.com/epp>FAQ http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON_FAQTechnical Service Request https://www.freescale.com/webapp/servicerequest.create_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod**LINKS TO BLANK IPC1752 FORMS**Blank IPC1752 v0.9 Form http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v0.9_MCD_Template.pdfBlank IPC1752 v1.1 Form http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MPXH6300AC6T1_IPC1752_v09.xml

http://www.freescale.com/mcds/MPXH6300AC6T1_IPC1752_v11.xml

http://www.freescale.com/mcds/MPXH6300AC6T1_IPC1752A.xml